

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6936989

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
XI'AN ESWIN SILICON WAFER TECHNOLOGY CO., LTD	09/06/2021
RECEIVING PARTY DATA	
Name:	XI'AN ESWIN MATERIAL TECHNOLOGY CO., LTD.
Street Address:	1888 SOUTH XIFENG RD, HI-TECH ZONE
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State/Country:	CHINA
Postal Code:	710000
Name:	XI'AN ESWIN SILICON WAFER TECHNOLOGY CO., LTD
Street Address:	1888 SOUTH XIFENG RD, HI-TECH ZONE
City:	XI'AN, SHAANXI
State/Country:	CHINA
Postal Code:	710000
PROPERTY NUMBERS Total: 3	
Property Type	Number
Application Number:	16912885
Application Number:	16918617
Application Number:	16918041
CORRESPONDENCE DATA	
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SIGNATURE:	/Harold C. Moore/
DATE SIGNED:	09/27/2021
Total Attachments: 1 source=US ASSIGNMENT ESWIN Silicon to Material+Silicon#page1.tif	

ASSIGNMENT OF PATENTS

WHEREAS, XI'AN ESWIN SILICON WAFER TECHNOLOGY CO., LTD., a Chinese corporation ("Assignor"), having an address of 1888 SOUTH XIFENG RD., HI-TECH ZONE, XI'AN, SHAANXI 710000, P.R.CHINA, is the owner of the entire right, title and interest (hereinafter "said right, title, and interest") in and to the United States Patent Applications listed in the following chart (hereinafter referred to as "said Patent Applications.")

Serial No.	Application Date	Country
16/912,885	26 Jun. 2020	US
16/918,617	1 Jul. 2020	US
16/918,041	1 Jul. 2020	US

AND WHEREAS, XI'AN ESWIN MATERIAL TECHNOLOGY CO., LTD., a Chinese corporation ("Assignee 1"), having an address of ROOM 1-3-029, NO.1888 SOUTH XIFENG RD, HI-TECH ZONE, XI'AN, SHAANXI 710000, P.R.CHINA, and XI'AN ESWIN SILICON WAFER TECHNOLOGY CO., LTD., a Chinese corporation ("Assignee 2"), having an address of 1888 SOUTH XIFENG RD., HI-TECH ZONE, XI'AN, SHAANXI 710000, P.R.CHINA, are desirous of acquiring said right, title, and interest in and to said Patent Applications.

AND WHEREAS, for good and valuable consideration, the receipt of which is hereby acknowledged, and intending to be legally bound hereby, Assignor hereby assigns and transfers to Assignees' said right, title, and interest in and to said Patent Applications and all rights thereto, including but not limited to all issues, reissues, divisions, continuations and extensions thereof, all copies and tangible embodiments thereof, all rights of action arising therefrom, all claims by reason of, and the right to collect damages for, the past, present or future infringement thereof, to be held and enjoyed by Assignees for their own use and benefit and for their successors and assigns as the same would have been held by Assignor had this assignment not been made.

XI'AN ESWIN SILICON WAFER TECHNOLOGY CO., LTD.

Signature: Xinyuan YANG

Printed Name: Xinyuan YANG, President

Date: 6 September 2021

XI'AN ESWIN MATERIAL TECHNOLOGY CO., LTD.

Signature: Xinyuan YANG

Printed Name: Xinyuan YANG, General Manager

Date: 6 September 2021